

[PROCESS AND STRUCTURE FOR SEMI-CONDUCTOR PACKAGE]

Abstract

A packaging process for a semiconductor chip that includes the following steps. A carrier having an upper surface and a corresponding lower surface is provided. A photoresist layer is formed on the upper surface of the carrier. A plurality of photoresist openings that expose the carrier is formed in the photoresist layer. A plurality of openings that connects with the photoresist openings are formed in the carrier. A tape is attached to the lower surface of the carrier. The body is filled into the openings of the carrier. A chip is mounted onto the upper surface of the carrier and electrically connected therewith. Finally, the tape is removed from the lower surface of the carrier.